

# SOT1322-1

plastic low profile fine-pitch ball grid array package; 223 balls, 0.65 mm pitch, 12 mm x 12 mm x 1.3 mm body

3 April 2017

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	LFPGA223
<b>Package type industry code</b>	LFPGA223
<b>Package style descriptive code</b>	LFPGA (low profile fine-pitch ball grid array)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	MO-205
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	25-1-2012
<b>Manufacturer package code</b>	SOT1322

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	11.9	-	12	12.1	mm
E	package width	11.9	-	12	12.1	mm
A	seated height	1.2	-	1.3	1.45	mm
A <sub>2</sub>	package height	0.95	-	1	1.1	mm
e	nominal pitch	-	-	0.65	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	223	-	



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2. Package outline

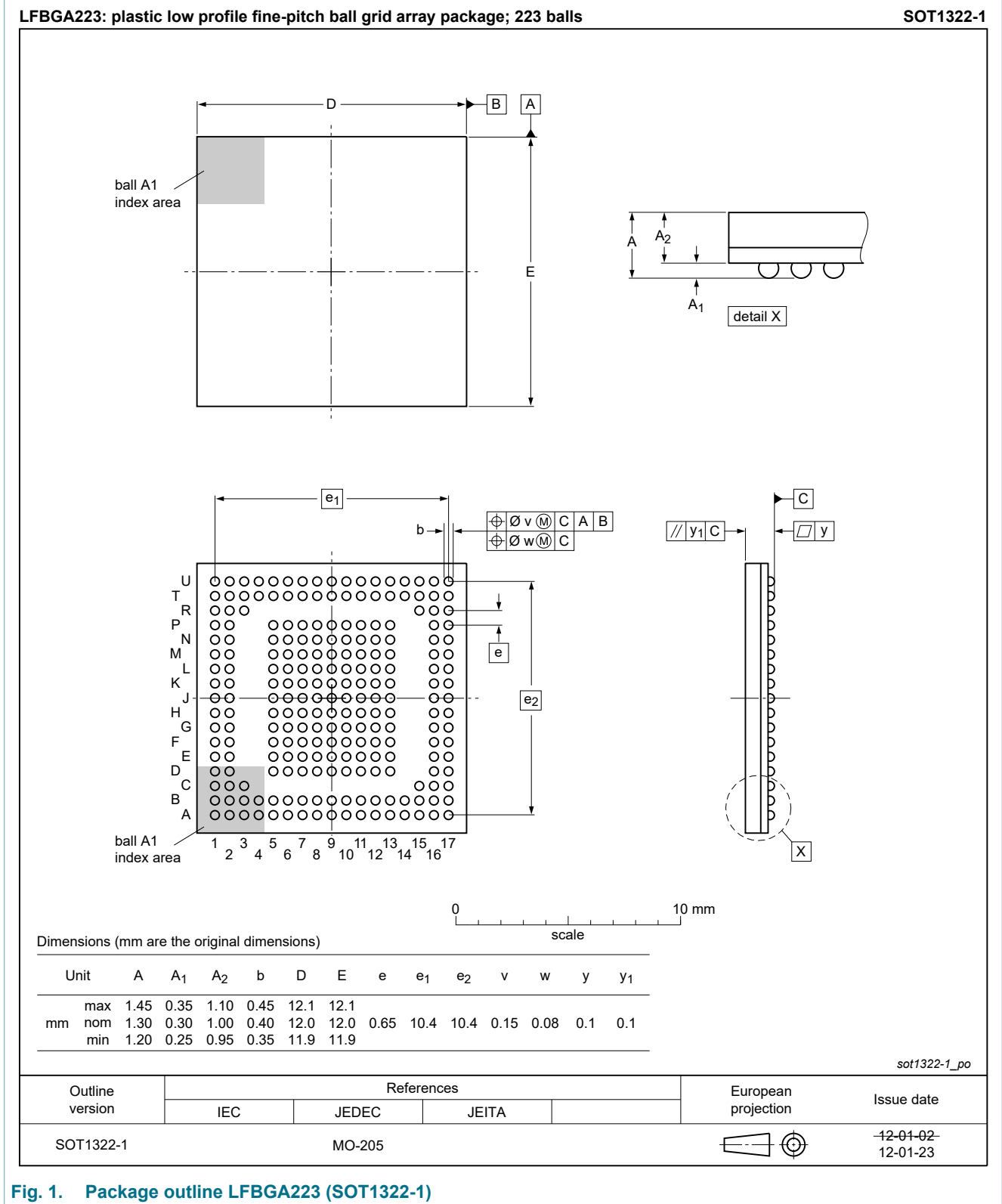


Fig. 1. Package outline LFBGA223 (SOT1322-1)

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### 3. Soldering

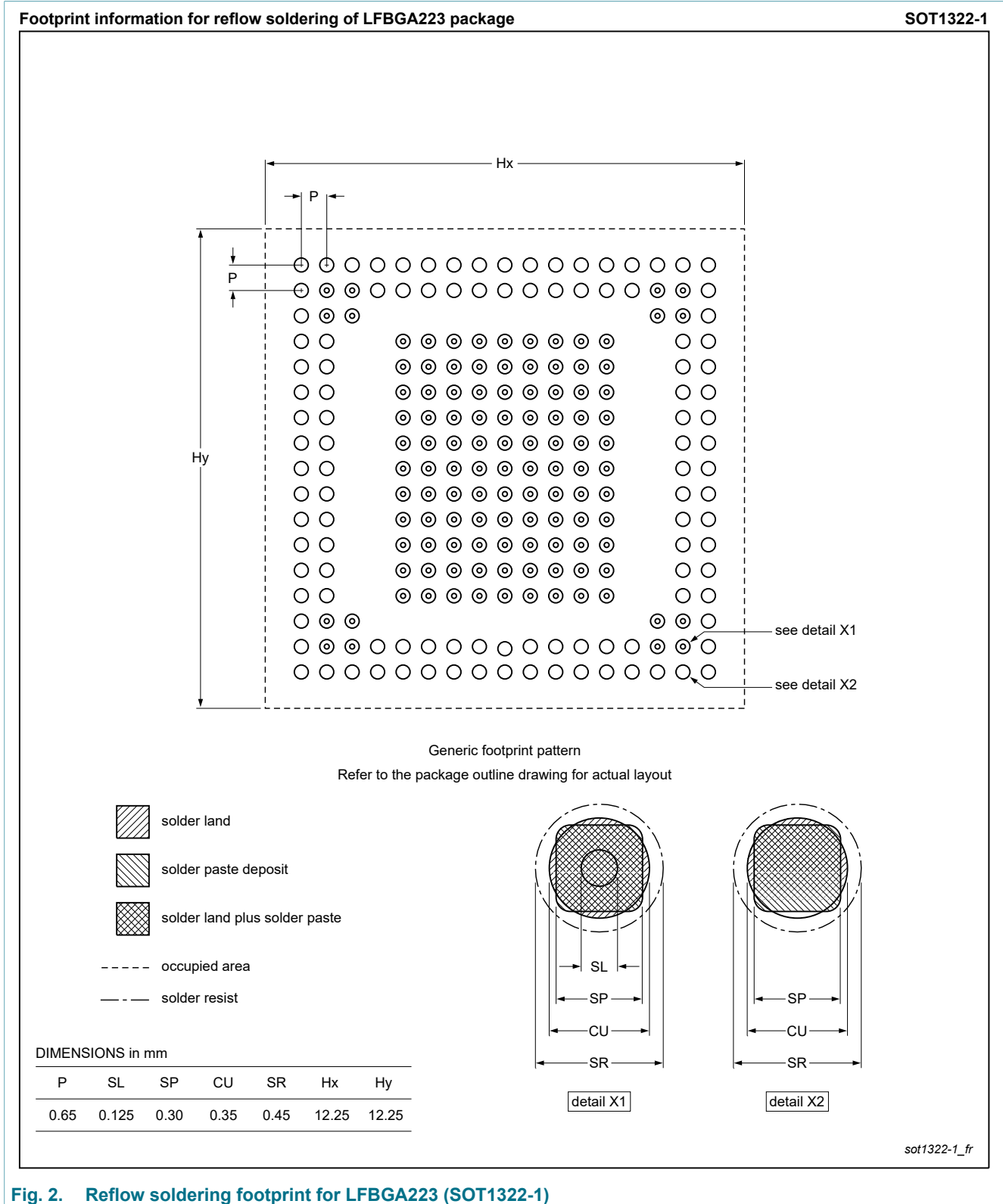


Fig. 2. Reflow soldering footprint for LFBGA223 (SOT1322-1)

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## 4. Legal information

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## 5. Contents

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1. Package summary.....	1
2. Package outline.....	2
3. Soldering.....	3
4. Legal information.....	4

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